

6367254 MOTOROLA SC (XSTRS/R F)

96D 81070 D T-33-13

MOTOROLA SEMICONDUCTOR TECHNICAL DATA

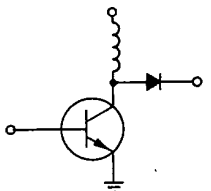
MJ13070
MJ13071

Designer's Data Sheet

SWITCHMODE II SERIES
NPN SILICON POWER TRANSISTORS

The MJ13070 and MJ13071 transistors are designed for high-voltage, high-speed, power switching in inductive circuits where fall time is critical. They are particularly suited for line-operated switch-mode applications such as:

- **Switching Regulators**
- **Inverters**
- **Solenoid and Relay Drivers**
- **Motor Controls**
- **Deflection Circuits**



Fast Turn-Off Times

100 ns Inductive Fall Time @ 25°C (Typ)
150 ns Inductive Crossover Time @ 25°C (Typ)
400 ns Inductive Storage Time @ 25°C (Typ)

Operating Temperature Range -65 to +200°C

100°C Performance Specified for:

- Reverse-Biased SOA with Inductive Loads
- Switching Times with Inductive Loads
- Saturation Voltages
- Leakage Currents

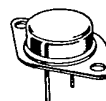
5 AMPERE

NPN SILICON POWER TRANSISTORS

**400 AND 450 VOLTS
125 WATTS**

Designer's Data for "Worst Case" Conditions

The Designer's Data Sheet permits the design of most circuits entirely from the information presented. Limit data — representing device characteristics boundaries — are given to facilitate "worst case" design.



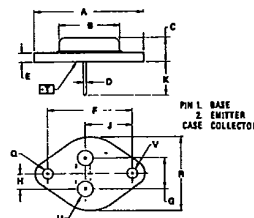
MAXIMUM RATINGS

Rating	Symbol	MJ13070	MJ13071	Unit
Collector-Emitter Voltage	V_{CEO}	400	450	Vdc
Collector-Emitter Voltage	V_{CEV}	650	750	Vdc
Emitter Base Voltage	V_{EB}	6.0		Vdc
Collector Current — Continuous — Peak (1)	I_C	5.0		Adc
	I_{CM}	8.0		
Base Current — Continuous — Peak (1)	I_B	2.0		Adc
	I_{BM}	4.0		
Total Power Dissipation @ $T_C = 25^{\circ}\text{C}$ @ $T_C = 100^{\circ}\text{C}$ Derate above 25°C	P_D	125		Watts
		71.5		
		0.714		
Operating and Storage Junction Temperature Range	T_J, T_{stg}	-65 to +200		$^{\circ}\text{C}$

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	1.4	$^{\circ}\text{C/W}$
Maximum Lead Temperature for Soldering Purposes: 1/8" from Case for 5 Seconds	T_L	275	$^{\circ}\text{C}$

(1) Pulse Test: Pulse Width = 5 ms, Duty Cycle $\leq 10\%$.



NOTES

1. DIMENSIONS Q AND V ARE DATUMS.
2. T IS SEATING PLANE AND DATUM.
3. POSITIONAL TOLERANCE FOR MOUNTING HOLE Q.

◆	13 (0.005)	Ⓜ	T	V	Ⓜ
---	------------	---	---	---	---

FOR LEADS

◆	13 (0.005)	Ⓜ	T	V	Ⓜ	Q	Ⓜ
---	------------	---	---	---	---	---	---

4. DIMENSIONS AND TOLERANCES PER
ANSI Y14.5, 1973.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	—	33.37	—	1.550
B	—	21.04	—	0.833
C	8.35	7.82	0.250	0.300
D	0.93	1.09	0.038	0.043
E	1.43	1.78	0.055	0.070
F	30.15 BSC		1.187 BSC	
G	10.92 BSC		0.430 BSC	
H	5.46 BSC		0.215 BSC	
J	16.89 BSC		0.665 BSC	
K	11.18	12.18	0.440	0.480
Q	3.81	8.19	0.150	0.325
R	—	26.87	—	1.050
U	4.83	5.33	0.190	0.210
V	3.81	8.19	0.150	0.325

**CASE 1-05
TO-204AA**

6367254 MOTOROLA SC (XSTRS/R F)
MJ13070, MJ13071

96D 81071 D

T-33-13

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS (1)					
Collector-Emitter Sustaining Voltage (Table 1) ($I_C = 100\text{ mA}$, $I_B = 0$)	MJ13070 MJ13071 $V_{CE(sus)}$	400 450	— —	— —	Vdc
Collector Cutoff Current ($V_{CEV} = \text{Rated Value}$, $V_{BE(off)} = 1.5\text{ Vdc}$) ($V_{CEV} = \text{Rated Value}$, $V_{BE(off)} = 1.5\text{ Vdc}$, $T_C = 100^\circ\text{C}$)	I_{CEV}	— —	— —	0.5 2.5	mAdc
Collector Cutoff Current ($V_{CE} = \text{Rated } V_{CEV}$, $R_{BE} = 50\ \Omega$, $T_C = 100^\circ\text{C}$)	I_{CER}	—	—	3.0	mAdc
Emitter Cutoff Current ($V_{EB} = 6.0\text{ Vdc}$, $I_C = 0$)	I_{EBO}	—	—	1.0	mAdc

SECOND BREAKDOWN

Second Breakdown Collector Current with Base Forward Biased	$I_{S/b}$	See Figure 12	
Clamped Inductive SOA with Base Reverse Biased	RBSOA	See Figure 13	

ON CHARACTERISTICS (1)

DC Current Gain ($I_C = 3.0\text{ Adc}$, $V_{CE} = 5.0\text{ Vdc}$)	h_{FE}	8.0	—	—	—
Collector-Emitter Saturation Voltage ($I_C = 3.0\text{ Adc}$, $I_B = 0.6\text{ Adc}$) ($I_C = 5.0\text{ Adc}$, $I_B = 1.0\text{ Adc}$) ($I_C = 3.0\text{ Adc}$, $I_B = 0.6\text{ Adc}$, $T_C = 100^\circ\text{C}$)	$V_{CE(sat)}$	— — —	— — —	1.0 3.0 2.0	Vdc
Base-Emitter Saturation Voltage ($I_C = 3.0\text{ Adc}$, $I_B = 0.6\text{ Adc}$) ($I_C = 3.0\text{ Adc}$, $I_B = 0.6\text{ Adc}$, $T_C = 100^\circ\text{C}$)	$V_{BE(sat)}$	— —	— —	1.5 1.5	Vdc

DYNAMIC CHARACTERISTICS

Output Capacitance ($V_{CB} = 10\text{ Vdc}$, $I_E = 0$, $f_{test} = 1.0\text{ kHz}$)	C_{ob}	—	—	250	pF
--	----------	---	---	-----	----

SWITCHING CHARACTERISTICS

Resistive Load (Table 1)					
Delay Time	($V_{CC} = 250\text{ Adc}$, $I_C = 3.0\text{ Adc}$, $I_{B1} = 0.4\text{ Adc}$, $t_p = 30\ \mu\text{s}$, Duty Cycle $\leq 2\%$, $V_{BE(off)} = 5.0\text{ Vdc}$)	t_d	—	0.03	0.05
Rise Time		t_r	—	0.10	0.40
Storage Time		t_s	—	0.40	1.50
Fall Time		t_f	—	0.175	0.50

Inductive Load, Clamped (Table 1)

Storage Time	($I_{C(pk)} = 3.0\text{ A}$, $I_{B1} = 0.4\text{ Adc}$, $V_{BE(off)} = 5.0\text{ Vdc}$, $V_{CE(pk)} = 250\text{ V}$)	$(T_J = 100^\circ\text{C})$	t_{sv}	—	0.70	2.0	μs
Crossover Time			t_c	—	0.28	0.50	
Fall Time		$(T_J = 25^\circ\text{C})$	t_{fi}	—	0.15	0.30	
Storage Time			t_{sv}	—	0.40	—	
Crossover Time			t_c	—	0.15	—	
Fall Time			t_{fi}	—	0.10	—	

(1) Pulse Test PW = 300 μs , Duty Cycle $\leq 2\%$

$$\beta_f = \frac{I_C}{I_B}$$

6367254 MOTOROLA SC (XSTRS/R F)

96D 81072 D

MJ13070, MJ13071

T-33-13

TYPICAL ELECTRICAL CHARACTERISTICS

FIGURE 1 — DC CURRENT GAIN

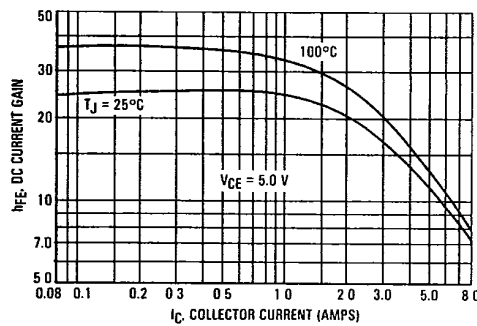


FIGURE 2 — COLLECTOR SATURATION REGION

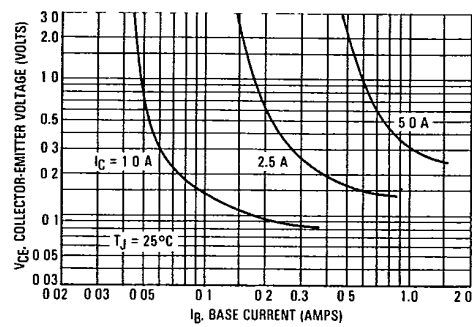


FIGURE 3 — COLLECTOR-EMITTER SATURATION VOLTAGE

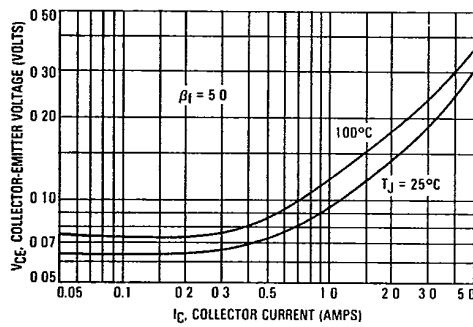


FIGURE 4 — BASE-EMITTER VOLTAGE

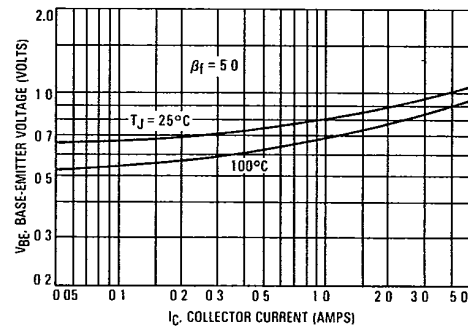


FIGURE 5 — COLLECTOR CUTOFF REGION

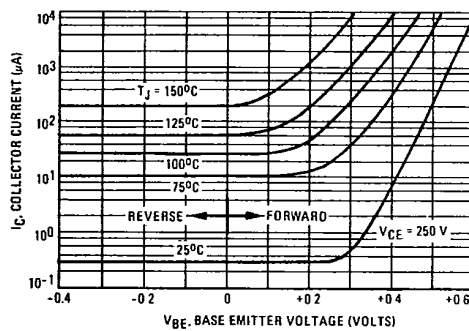
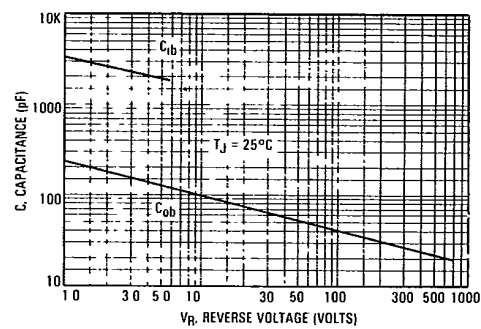


FIGURE 6 — CAPACITANCE



6367254 MOTOROLA SC (XSTRS/R F)

96D 81074 D

MJ13070, MJ13071

T-33-13

SWITCHING TIMES NOTE

In resistive switching circuits, rise, fall, and storage times have been defined and apply to both current and voltage waveforms since they are in phase. However, for inductive loads which are common to SWITCHMODE power supplies and hammer drivers, current and voltage waveforms are not in phase. Therefore, separate measurements must be made on each waveform to determine the total switching time. For this reason, the following new terms have been defined.

t_{SV} = Voltage Storage Time, 90% I_{B1} to 10% V_{clamp}

t_{rv} = Voltage Rise Time, 10–90% V_{clamp}

t_{fi} = Current Fall Time, 90–10% I_C

t_{ti} = Current Tail, 10–2% I_C

t_c = Crossover Time, 10% V_{clamp} to 10% I_C

An enlarged portion of the inductive switching waveforms

is shown in Figure 7 to aid in the visual identity of these terms.

For the designer, there is minimal switching loss during storage time and the predominant switching power losses occur during the crossover interval and can be obtained using the standard equation from AN-222:

$$P_{SWT} = 1/2 V_{CC} I_C (t_c) f$$

In general, $t_{rv} + t_{fi} \approx t_c$. However, at lower test currents this relationship may not be valid.

As is common with most switching transistors, resistive switching is specified at 25°C and has become a benchmark for designers. However, for designers of high frequency converter circuits, the user oriented specifications which make this a "SWITCHMODE" transistor are the inductive switching speeds (t_c and t_{SV}) which are guaranteed at 100°C.

INDUCTIVE SWITCHING

FIGURE 9 — STORAGE TIME

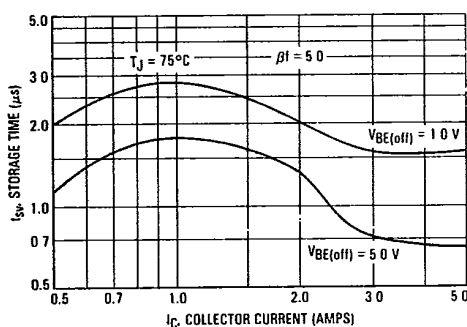


FIGURE 10 — CROSSOVER AND FALL TIMES

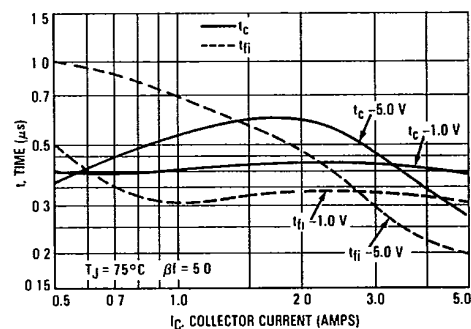
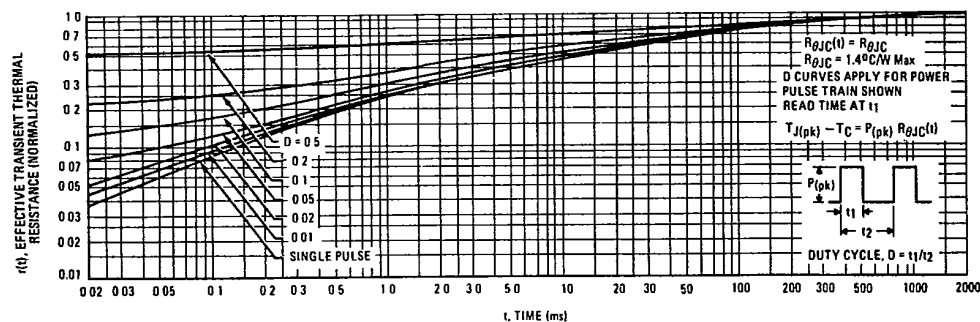


FIGURE 11 — THERMAL RESPONSE



6367254 MOTOROLA SC (XSTRS/R F)

96D 81075 D

MJ13070, MJ13071

T-33-13

The Safe Operating Area figures shown in Figures 12 and 13 are specified for these devices under the test conditions shown.

FIGURE 12 — MAXIMUM RATED FORWARD BIAS SAFE OPERATING AREA

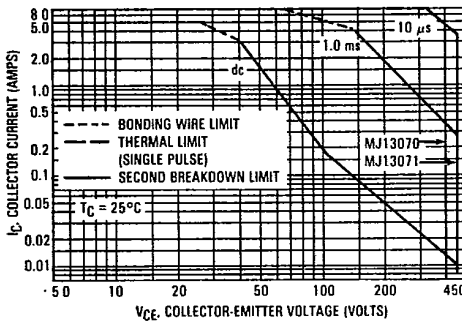
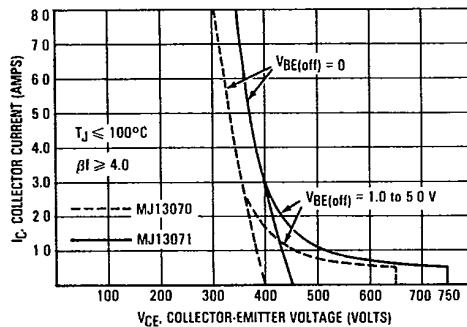


FIGURE 13 — MAXIMUM RATED REVERSE BIAS SAFE OPERATING AREA



SAFE OPERATING AREA INFORMATION

FORWARD BIAS

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate I_C - V_{CE} limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 12 is based on $T_C = 25^\circ\text{C}$; $T_J(pk)$ is variable depending on power level. Second breakdown pulse limits are valid for duty cycles to 10% but must be derated when $T_C \geq 25^\circ\text{C}$. Second breakdown limitations do not derate the same as thermal limitations. Allowable current at the voltages shown on Figure 12 may be found at any case temperature by using the appropriate curve on Figure 14.

$T_J(pk)$ may be calculated from the data in Figure 11. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

REVERSE BIAS

For inductive loads, high voltage and high current must be sustained simultaneously during turn-off, in most cases, with the base to emitter junction reverse biased. Under these conditions the collector voltage must be held to a safe level at or below a specific value of collector current. This can be accomplished by several means such as active clamping, RC snubbing, load line shaping, etc. The safe level for these devices is specified as Reverse Bias Safe Operating Area and represents the voltage-current conditions during reverse biased turn-off. This rating is verified under clamped conditions so that the device is never subjected to an avalanche mode. Figure 13 gives RBSOA characteristics.

FIGURE 14 — POWER DERATING

